HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>screw driver</td>
<td>#1</td>
</tr>
<tr>
<td>tear down stick</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove base screws 7pcs
2. Disassemble base cover from the unit.(rear side use tear down stick)
3. Take off 4 pcs of screws which fastening battery to Top Assy. and then disassemble the Battery.
4. Remove HDD and HDD cable.(3 screws)
5. Remove KB BL FPC, KB MEM, TP FFC, LCD cable’s MB side, Antenna cable’s MB side, DB to MB FFC, speaker cable.
6. Remove 2 pcs of screws and disassemble DB.
7. Remove 8 pcs of screws and disassemble thermal module.
8. Loose 5pcs screws and remove fan cables and 2 fans.
9. Remove 1 pcs screw and disassemble Wlan module from MB.
10. Remove 1 pcs screw and disassemble SSD module from MB.
11. Remove RAM module from MB.
12. Remove DC -in cable, DB to MB FFC from MB.
13. Loose 5pcs screws whiching fastening MB on top Assy and take MB off from top-assy.
14. Remove 2 pcs screw and Disassemble speaker R and L from top-assy.
15. Loose 3pcs screws whiching fastening TP support on top-assy and take off TP support BKT from top-assy.
16. Loose 3pcs screws whiching fastening TP and TP holder assy and take this assy from top-assy.
17. Remove 6pcs of screws and disassemble the display unit from top-assy.(The LCD must open to max angle for disassemble)
18. Disassemble LCD bezel from display unit.
19. Tear off the 2 pcs reworkable tape from LCD upper side. and take it off from LCD cover. Before removing LCD module, separate LCD cable from LCD module.
20. Loose 5 pcs of screws which fasetening Hinge R from LCD cover and remove hinge R from LCD cover.
21. Loose 5 pcs of screws which fasetening Hinge L from LCD cover and remove hinge L from LCD cover.
22. Separate LCD cable from camera module and remove both from LCD cover.
23. Remove antenna cable from LCD cover.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

3.22 Remove base cover.

3.23 Remove Battery

3.24 DB and HDD assy
3.25 Display unit

3.27 Thermal module and Fan

3.28 MB, Wlan module and SSD module

3.29 DC-IN CABLE and DB to MB FFC from MB.

HPI instructions for this template are available at EL-MF877-01
3.30 Ram, Speaker R & L.

3.31 TP support BKT and TP holder asy.

3.32 LCD Bezel

3.33 LCD cover and LCD module
3.34 Hinge R and L

3.35 LCD cable, Antenna cable and Camera module